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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/664,875	09/22/2003	Naoteru Matsubara	65933-044	4231
	7590 12/18/2006 , WILL & EMERY	EXAMINER		
600 13th Street, N.W.			IM, JUNGHWA M	
Washington, DC 20005-3096			ART UNIT	PAPER NUMBER
			2811	
SHORTENED STATUTOR	Y PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE	
3 MONTHS		12/18/2006	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

	Application No.	Applicant(s)			
	10/664,875	MATSUBARA ET AL.			
Office Action Summary	Examiner	Art Unit			
	Junghwa M. Im	2811			
The MAILING DATE of this communication	1 -	ith the correspondence address			
Period for Reply A SHORTENED STATUTORY PERIOD FOR R THE MAILING DATE OF THIS COMMUNICATION Extensions of time may be available under the provisions of 37 Cafter SIX (6) MONTHS from the mailing date of this communication If the period for reply specified above is less than thirty (30) days, If NO period for reply is specified above, the maximum statutory provided to the period for reply within the set or extended period for reply will, by any reply received by the Office later than three months after the earned patent term adjustment. See 37 CFR 1.704(b).	ON. FR 1.136(a). In no event, however, may a on. a reply within the statutory minimum of thir period will apply and will expire SIX (6) MON statute, cause the application to become Al	reply be timely filed ty (30) days will be considered timely. NTHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).			
Status	•				
1) Responsive to communication(s) filed on	<u>9/18/2006</u> .				
2a) ☐ This action is FINAL . 2b) ☑)☐ This action is FINAL . 2b)☑ This action is non-final.				
3) Since this application is in condition for all	owance except for formal mat	ters, prosecution as to the merits is			
closed in accordance with the practice und	der <i>Ex parte Quayle</i> , 1935 C.D). 11, 453 O.G. 213.			
Disposition of Claims					
4) ☐ Claim(s) 1-22 is/are pending in the applicate 4a) Of the above claim(s) 6-17 is/are without 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-5 and 18-22 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction a	Irawn from consideration.				
Application Papers					
9)☐ The specification is objected to by the Exa	miner.				
10) ☐ The drawing(s) filed on 22 September 200	$\underline{3}$ is/are: a) $⊠$ accepted or b) $$	objected to by the Examiner.			
Applicant may not request that any objection to	the drawing(s) be held in abeyar	nce. See 37 CFR 1.85(a).			
Replacement drawing sheet(s) including the continuous The oath or declaration is objected to by the	•	· · · · · · · · · · · · · · · · · · ·			
Priority under 35 U.S.C. § 119					
12) △ Acknowledgment is made of a claim for for a) △ All b) ☐ Some * c) ☐ None of: 1. △ Certified copies of the priority docur 2. ☐ Certified copies of the priority docur 3. ☐ Copies of the certified copies of the application from the International But * See the attached detailed Office action for a	ments have been received. ments have been received in A priority documents have been ureau (PCT Rule 17.2(a)).	application No received in this National Stage			
Attachment(s)					
 Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO-94) 	4) Interview S	Summary (PTO-413) s)/Mail Date			
 Notice of Dransperson's Patent Drawing Review (PTO-94) Information Disclosure Statement(s) (PTO-1449 or PTO/S Paper No(s)/Mail Date 9/2006. 		nformal Patent Application (PTO-152)			
J.S. Patent and Trademark Office PTOL-326 (Rev. 1-04) Office	ce Action Summary	Part of Paper No./Mail Date 20061209			

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DETAILED ACTION

Continued Examination Under 37 CFR 1.114

A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on September 18, 2006 has been entered.

Claim Objections

Claims 4 and 21 are objected to because of the following informalities: The term "second dielectric Films" in claims 4 and 23 should be -- second dielectric films--.

Appropriate correction is required.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-5 and 18-22 are rejected under 35 U.S.C. 103(a) as being unpatentable over Gates et al. (US Pat. 6,603,204), hereinafter Gates in view of Ma et al. (US Pat. 6,764,810), hereinafter Ma.

Regarding claims 1 and 18, Fig. 8 of Gates shows a semiconductor device comprising:

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a semiconductor substrate [50];

a multilayered film including a first dielectric film [54'], an etching stopper [56'] and a second dielectric film [58'] stacked on said semiconductor substrate in this order; and

a via plug [a narrow portion of the metal layer 74 in the layer 54'] and a metal interconnect [a wide portion of the metal layer 74 in the layer 58'], which is formed on the via plug, formed in said multilayered film, wherein

the dielectric constant [k] of said etching stopper is larger than that of said first and second dielectric films (k=1.4-3.5 for the first and second dielectric films, k=1.1-5.5 for etching stopper; col. 4, lines 9-64).

Fig. 8 of Gates shows most aspects of the instant invention except "the upper surface of said etching stopper is located under the upper surface level of said metal interconnect, the under surface of said etching stopper is located over the under surface level of said metal interconnect, and the under surface of said metal interconnect is located inside the first dielectric film."

Figure 1H of Ma shows a metal interconnect [a wider portion of the trench 20] wherein the upper surface of the etching stopper [14; col. 5, lines 57-59] is located under the upper surface level of said metal interconnect, the under surface of said etching stopper is located over the under surface level of said metal interconnect, and the under surface of said metal interconnect is located inside the first dielectric film [12].

It would have been obvious to one of ordinary skill in the art at the time of the invention was made to incorporate the teachings of Ma into the device of Gates in order to have the upper surface of the etching stopper located under the upper surface level of said metal interconnect, the under surface of the etching stopper located over the under surface level of the metal

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interconnect, and the under surface of the metal interconnect located inside the first dielectric film to reduce a problem caused by residual masking material.

Regarding claims 2 and 19, Gates discloses the semiconductor device wherein the dielectric constant [k=1.1-5.5] of said etching stopper is less than or equal to 5 (col. 4, lines 60-64).

Regarding claims 3, 4, 20 and 21, Gates discloses the semiconductor device wherein the dielectric constant of said etching stopper is larger than or equal to a summation of 2 and the dielectric constant of either one of the dielectric constants [k=1.4-3.5] of said first and second dielectric films (col. 4, lines 15-20).

Regarding claims 5 and 22, Gates discloses said metal interconnect includes copper as a constituting element (col. 7, lines 30-35).

Response to Arguments

Applicant's arguments with respect to pending claims have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Junghwa M. Im whose telephone number is (571) 272-1655. The examiner can normally be reached on MON.-FRI. 8:30AM-5:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Richard T. Elms can be reached on (571) 272-1869. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Junghwa M. Im

Examiner

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jmi

12/9/2006